IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ials and Mfc Information			
upplier Inform														
Company name*			Company unique ID			τ	Unique ID Authority				Response Date*			
onsemi											2024-05-18			
Contact Name		Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-Env-Stewa	ards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
uthorized Represe	ntative*	Title - Representative			1	Phone - Representative*				Email - Representative*				
Product-Env-Stewa	ırds	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requeste	Requester Item Number Mfr Item		m Number Mfr Item Name				Effective Date	Versio	Yersion Manufacturing Site			Weight*	UOM	Unit Type
		NCV-RSL10-101Q48- AVG RSL10 QFN for Automotive		Automotive		2024-05-18			TWU		137.17	mg	Each	
Ianufacturing	Proccess Informatio	n												
Terminal Plating / Grid Array Material Te			Ferminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperature Max Time at Pea		x Tempera	ture Numb	er of Reflow Cyc	cles			
Matte Tin (Sn) - annealed		C	CU Alloy 1			260 C 30		30	seconds 3					
omments														
vel 1 - maximum t	ime at peak temperature	during sol	dering is 10-3	0 seconds										
or more informati	on regarding material cor	nposition 1	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.46	mg	Supplier	Silicon (Si)	7440-21-3		4.46	mg
Die Attach	1.9	mg	Supplier	Isobornyl Methacrylate	7534-94-3		0.114	mg
			Supplier	Silver (Ag)	7440-22-4		1.5485	mg
			Supplier	Isobornyl Acrylate	5888-33-5		0.114	mg
			Supplier	Misc.	Proprietary Data		0.0095	mg
			Supplier	Tricyclo[5.2.1.02,6]decanedimethanol Diacrylate (C18H24O4)	42594-17-2		0.114	mg
Lead Frame	66.33	mg	Supplier	Tin (Sn)	7440-31-5		0.1658	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1459	mg
			Supplier	Chromium (Cr)	7440-47-3		0.1658	mg
			Supplier	Copper (Cu)	7440-50-8		65.8524	mg
Lead Frame plating	0.29	mg	Supplier	Silver (Ag)	7440-22-4		0.29	mg
Mold Compound-Black	58.76	mg	Supplier	Epoxy resins	129915-35-1		2.938	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		2.938	mg
			Supplier	Carbon Black (C)	1333-86-4		0.235	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		1.3515	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		49.946	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.3515	mg
Plating	4.24	mg	Supplier	Tin (Sn)	7440-31-5		4.24	mg
Wire Bond - Au	1.19	mg	Supplier	Gold (Au)	7440-57-5		1.19	mg